## **General Purpose Transistors**

## **PNP Silicon**

#### **Features**

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

| Rating                            | Symbol           | Value | Unit |
|-----------------------------------|------------------|-------|------|
| Collector – Emitter Voltage       | $V_{CEO}$        | -60   | Vdc  |
| Collector - Base Voltage          | V <sub>CBO</sub> | -60   | Vdc  |
| Emitter-Base Voltage              | V <sub>EBO</sub> | -5.0  | Vdc  |
| Collector Current – Continuous    | Ic               | -600  | mAdc |
| Collector Current – Peak (Note 3) | I <sub>CM</sub>  | -1200 | mAdc |

#### THERMAL CHARACTERISTICS

| Characteristic  | Symbol                            | Max         | Unit        |
|---|-----------------------------------|-------------|-------------|
| Total Device Dissipation – FR–5 Board<br>(Note 1) @T <sub>A</sub> = 25°C<br>Derate above 25°C         | P <sub>D</sub>                    | 225<br>1.8  | mW<br>mW/°C |
| Thermal Resistance, Junction-to-Ambient   | $R_{\theta JA}$                   | 556         | °C/W        |
| Total Device Dissipation – Alumina<br>Substrate, (Note 2) @T <sub>A</sub> = 25°C<br>Derate above 25°C | P <sub>D</sub>                    | 300<br>2.4  | mW<br>mW/°C |
| Thermal Resistance, Junction-to-Ambient   | $R_{\theta JA}$                   | 417         | °C/W        |
| Total Device Dissipation – Heat Spreader or equivalent, (Note 4) @T <sub>A</sub> = 25°C               | P <sub>D</sub>                    | 350         | mW          |
| Thermal Resistance, Junction-to-Ambient   | $R_{\theta JA}$                   | 357         | °C/W        |
| Junction and Storage Temperature  | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C          |

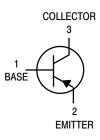
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.
- 3. Reference SOA curve.
- 4. Heat Spreader or equivalent = 450 mm<sup>2</sup>, 2 oz.



## ON Semiconductor®

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SOT-23 (TO-236AB) CASE 318 STYLE 6

#### **MARKING DIAGRAM**



2F = Device Code M = Date Code\* • = Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

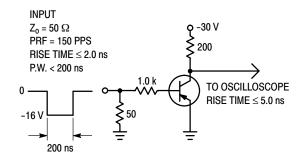
| Device         | Package   | Shipping <sup>†</sup> |
|----------------|-----------|-----------------------|
| MMBT2907ALT1G  | SOT-23    | 3000 / Tape &         |
| SMMBT2907ALT1G | (Pb-Free) | Reel                  |
| MMBT2907ALT3G  | SOT-23    | 10,000 / Tape &       |
| SMMBT2907ALT3G | (Pb-Free) | Reel                  |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

| Charac   | teristic   | Symbol               | Min                           | Max                | Unit |
|--|--|----------------------|-------------------------------|--------------------|------|
| OFF CHARACTERISTICS  |  | ·                    |                               | -L                 | 1    |
| Collector-Emitter Breakdown Voltage (No $(I_C = -1.0 \text{ mAdc}, I_B = 0)$ $(I_C = -10 \text{ mAdc}, I_B = 0)$   | te 5)  | V <sub>(BR)CEO</sub> | -60<br>-60                    | -<br>-             | Vdc  |
| Collector – Base Breakdown Voltage (I <sub>C</sub> :   | = -10 μAdc, I <sub>E</sub> = 0)  | V <sub>(BR)CBO</sub> | -60                           | -                  | Vdc  |
| Emitter – Base Breakdown Voltage (I <sub>E</sub> = -   | -10 μAdc, I <sub>C</sub> = 0)  | V <sub>(BR)EBO</sub> | -5.0                          | -                  | Vdc  |
| Collector Cutoff Current (V <sub>CE</sub> = −30 Vdc,   | $V_{EB(off)} = -0.5 \text{ Vdc}$   | I <sub>CEX</sub>     | -                             | -50                | nAdc |
| Collector Cutoff Current ( $V_{CB} = -50 \text{ Vdc}$ , $I_E = 0$ ) ( $V_{CB} = -50 \text{ Vdc}$ , $I_E = 0$ , $T_A = 125^{\circ}\text{C}$ )   |  | I <sub>CBO</sub>     | -<br>-                        | -0.010<br>-10      | μAdc |
| Base Cutoff Current (V <sub>CE</sub> = -30 Vdc, V <sub>EI</sub>  | $B_{\text{Off}} = -0.5 \text{ Vdc}$  | I <sub>BL</sub>      | -                             | -50                | nAdc |
| ON CHARACTERISTICS   |  |                      |                               |                    |      |
| DC Current Gain $ \begin{aligned} &(I_C = -0.1 \text{ mAdc},  V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -1.0 \text{ mAdc},  V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -10 \text{ mAdc},  V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -150 \text{ mAdc},  V_{CE} = -10 \text{ Vdc}) \\ &(I_C = -500 \text{ mAdc},  V_{CE} = -10 \text{ Vdc}) \end{aligned} $ | te 5)  | h <sub>FE</sub>      | 75<br>100<br>100<br>100<br>50 | -<br>-<br>300<br>- | -    |
| Collector – Emitter Saturation Voltage (Note 5)<br>( $I_C = -150 \text{ mAdc}$ , $I_B = -15 \text{ mAdc}$ ) (Note 5)<br>( $I_C = -500 \text{ mAdc}$ , $I_B = -50 \text{ mAdc}$ )   |  | V <sub>CE(sat)</sub> |                               | -0.4<br>-1.6       | Vdc  |
| Base – Emitter Saturation Voltage (Note 5)<br>( $I_C = -150$ mAdc, $I_B = -15$ mAdc)<br>( $I_C = -500$ mAdc, $I_B = -50$ mAdc)   |  | V <sub>BE(sat)</sub> | -<br>-                        | -1.3<br>-2.6       | Vdc  |
| SMALL-SIGNAL CHARACTERISTICS   |  |                      |                               | •                  | •    |
| Current – Gain – Bandwidth Product (Notes 5, 6),<br>(I <sub>C</sub> = –50 mAdc, V <sub>CE</sub> = –20 Vdc, f = 100 MHz)  |  | f <sub>T</sub>       | 200                           | _                  | MHz  |
| Output Capacitance (V <sub>CB</sub> = -10 Vdc, I <sub>E</sub> :  | = 0, f = 1.0 MHz)  | C <sub>obo</sub>     | -                             | 8.0                | pF   |
| Input Capacitance ( $V_{EB} = -2.0 \text{ Vdc}$ , $I_{C} = 0$ , $f = 1.0 \text{ MHz}$ )  |  | C <sub>ibo</sub>     | _                             | 30                 |      |
| SWITCHING CHARACTERISTICS  |  |                      |                               |                    |      |
| Turn-On Time   |  | t <sub>on</sub>      | ı                             | 45                 |      |
| Delay Time   | $(V_{CC} = -30 \text{ Vdc}, I_{C} = -150 \text{ mAdc}, I_{B1} = -15 \text{ mAdc})$         | t <sub>d</sub>       | _                             | 10                 |      |
| Rise Time  | ,  | t <sub>r</sub>       | _                             | 40                 | no   |
| Turn-Off Time  |  | t <sub>off</sub>     | -                             | 100                | ns   |
| Storage Time   | $(V_{CC} = -6.0 \text{ Vdc}, I_C = -150 \text{ mAdc}, I_{B1} = I_{B2} = -15 \text{ mAdc})$ | t <sub>s</sub>       | _                             | 80                 |      |
| Fall Time  | .61 – .62 – .0 (00)  | t <sub>f</sub>       | -                             | 30                 |      |

- 5. Pulse Test: Pulse Width  $\leq 300 \,\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .
- 6.  $f_T$  is defined as the frequency at which  $|h_{fe}|$  extrapolates to unity.





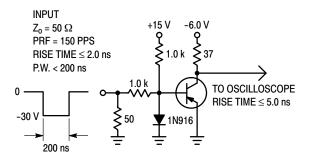


Figure 2. Storage and Fall Time Test Circuit

#### **TYPICAL CHARACTERISTICS**

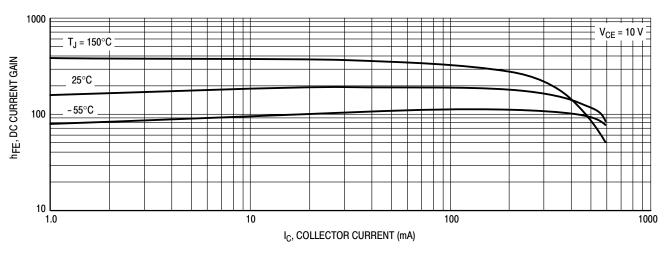


Figure 3. DC Current Gain

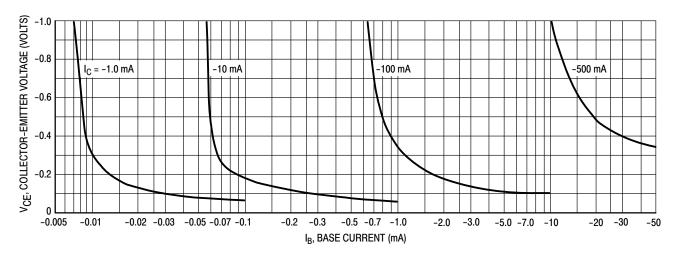


Figure 4. Collector Saturation Region

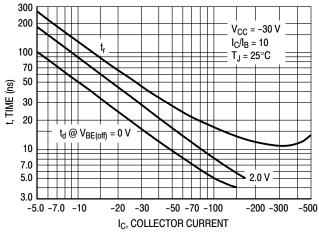


Figure 5. Turn-On Time

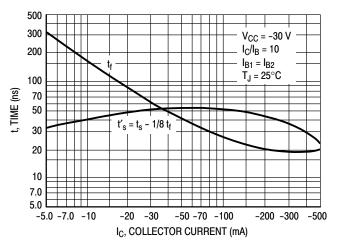
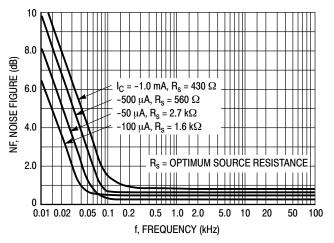


Figure 6. Turn-Off Time

# TYPICAL SMALL-SIGNAL Characteristics NOISE FIGURE

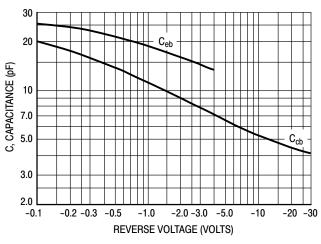
 $V_{CE}$  = 10 Vdc,  $T_A$  = 25°C



8.0 NF, NOISE FIGURE (dB) 6.0  $I_C = -50 \mu A$ -100 μA -500 μA 4.0 1.0 mA 2.0 100 200 2.0 k 50 k **5**0 1.0 k 5.0 k 10 k 20 k R<sub>s</sub>, SOURCE RESISTANCE (OHMS)

Figure 7. Frequency Effects

Figure 8. Source Resistance Effects



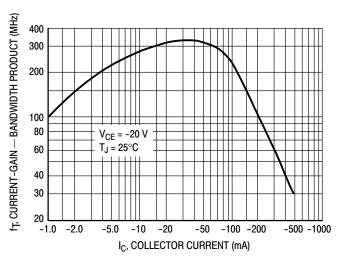
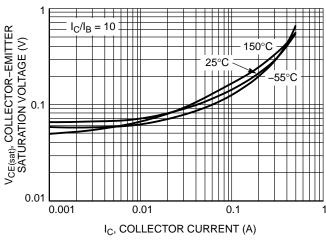


Figure 9. Capacitances

Figure 10. Current-Gain - Bandwidth Product



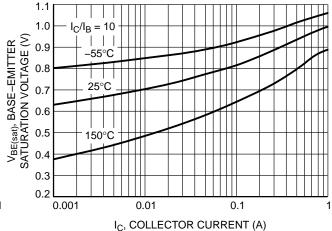
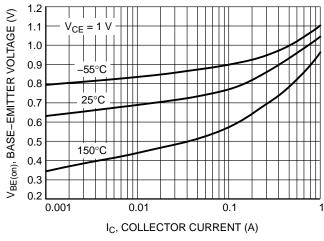


Figure 11. Collector Emitter Saturation Voltage vs. Collector Current

Figure 12. Base Emitter Saturation Voltage vs.
Collector Current

# TYPICAL SMALL-SIGNAL Characteristics NOISE FIGURE

 $V_{CE}$  = 10 Vdc,  $T_A$  = 25°C



+0.5

0

R<sub>0</sub>VC for V<sub>CE(sat)</sub>

-1.5

-2.0

R<sub>0</sub>VB for V<sub>BE</sub>

-2.5

-0.1 -0.2 -0.5 -1.0 -2.0 -5.0 -10 -20 -500

I<sub>C</sub>, COLLECTOR CURRENT (mA)

Figure 13. Base Emitter Voltage vs. Collector Current

Figure 14. Temperature Coefficients

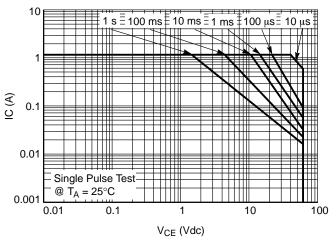


Figure 15. Safe Operating Area

**MILLIMETERS** 

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40

\_\_\_





#### SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

**DATE 14 AUG 2024** 

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

0.55

0.69

2.64

10°





DETAIL "A" Scale 3:1







#### NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

## **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

#### RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **STYLES ON PAGE 2**

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<sup>\*</sup>This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

| STYLE 1 THRU 5:<br>CANCELLED                            | STYLE 6:<br>PIN 1. BASE<br>2. EMITTER<br>3. COLLECTOR |               |   |   |
|---|---|---------------|---|---|
| STYLE 9:<br>PIN 1. ANODE<br>2. ANODE<br>3. CATHODE      | STYLE 10:<br>PIN 1. DRAIN<br>2. SOURCE<br>3. GATE     | 2. CATHODE 2. | 2: STYLE 13: CATHODE PIN 1. SOURCE CATHODE 2. DRAIN ANODE 3. GATE                 | STYLE 14:<br>PIN 1. CATHODE<br>2. GATE<br>3. ANODE          |
| STYLE 15:<br>PIN 1. GATE<br>2. CATHODE<br>3. ANODE      | STYLE 16:<br>PIN 1. ANODE<br>2. CATHODE<br>3. CATHODE | 2. ANODE 2.   | 3: STYLE 19: NO CONNECTION PIN 1. CATHODE CATHODE 2. ANODE ANODE 3. CATHODE-ANODE | STYLE 20:<br>PIN 1. CATHODE<br>2. ANODE<br>3. GATE          |
| STYLE 21:<br>PIN 1. GATE<br>2. SOURCE<br>3. DRAIN       | STYLE 22:<br>PIN 1. RETURN<br>2. OUTPUT<br>3. INPUT   |               |   | STYLE 26:<br>PIN 1. CATHODE<br>2. ANODE<br>3. NO CONNECTION |
| STYLE 27:<br>PIN 1. CATHODE<br>2. CATHODE<br>3. CATHODE | STYLE 28:<br>PIN 1. ANODE<br>2. ANODE<br>3. ANODE     |               |   |   |

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